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Subject: Notification of call for applications for International Exchange Program of the Engineering Schools

Call for Applications

International Exchange Program (Outbound) of the Engineering Schools

We are pleased to announce a call for applications for the **International Exchange Program (Outbound) of the Engineering Schools**. Students who wish to apply for this exchange program must submit the below documents to the International Cooperation Office of the Engineering Schools.

Before applying, students must read through [the website](http://www.eng3.e.titech.ac.jp/~inter/inter-e-exchange.html) and comply with the guidelines.
<http://www.eng3.e.titech.ac.jp/~inter/inter-e-exchange.html>

- ◆ **Program Categories Open for Application: (C2) ~ (C4)**
 - ◆ **Period of start studying abroad: Between December 2018 ~ March 2019**
*The period of stay shall not be less than 2 months.
 - ◆ **Prospective Applicants: Students who are enrolled in a master's or doctoral degree program at the Engineering Schools (School of Engineering, School of Materials and Chemical Technology, and School of Environment and Society.) as of September 1, 2018**
 - Students who will enter the Schools in September 2018 are **NOT** eligible.
 - Working adult students are **NOT** eligible.
 - ◆ **Deadline: 17:00 on Wednesday, September 19, 2018**
 - Applications that arrive after this deadline will not be processed, regardless of reason.
 - ◆ **Interview: Afternoon on Wednesday, September 26, 2018**
 - Details regarding location and time for the interview will be notified by email after the submission of the application documents.
 - If an applicant is unable to attend the interview for legitimate reasons, the [Statement of Reason](#) must be submitted with the other application documents to request the interview to be scheduled for a different time. The applicant may not request to reschedule the interview after the submission of the application.
 - ◆ **Application Documents:**
 - ✓ Incomplete applications and applications received after the deadline will not be accepted under any circumstances.
 - ✓ Submitted documents will not be returned.
- 1) [Application form](#) (Please use the latest version.)
 - 2) Resume in English (Free format. Click [here](#) for sample resume.)
 - 3) A copy of your English language test scores (TOEFL® or TOEIC® score report)
 - a. Some universities may have their own English language requirements, such as TOEFL iBT® or IELTS scores. The applicant must check with the university in which he/she wishes to enroll.
 - b. Applicants may submit a new, better score report to the interviewers in person during the interview.
 - 4) Academic Transcript in English(and Japanese if any)
The transcript must include your academic record of the previous year. Students in their first year of a master's degree program must attach their undergraduate final grade academic transcripts.
 - 5) [Recommendation Letter](#) by Academic Supervisor (Please use the latest version.)
 - 6) Statement of Reason (Free format)

- C3-b applicants who cannot apply for or was rejected by the [university-wide program conducted by International Student Exchange Division](#) (See the link)
 - All C4 applicants (Both by applicants and by their Chair of Department, Head of Graduate Studies or academic supervisor)
- 7) A copy of the email that shows the applicant get acceptance consent from a host professor
- All C3 and C4 applicants
 - Some C2 applicants who already have the consent above for any reason

◆ How to Submit the Application Documents

- Hard copies of documents 1), 2), 3), 4) 5) (and 6), 7) if applicable) above must be submitted by campus mail or by hand to the International Cooperation Office of the Engineering Schools.
- The documents must be single-sided A4 copies. Clip all sheets together.
- Documents 1) [Word], and 2) [PDF] above must **also** be submitted **by email**.

◆ Where to Submit or Inquire

International Cooperation Office, Engineering Schools
 Main Bldg., Floor 2, Rm 250 [Mailbox: H-106]
 ☎ 3969 ✉ ko.intl@jim.titech.ac.jp

◆ Application Guidelines

Program Outline	The Engineering Schools offer an international exchange program that consists of five categories, (C1), (C2), (C3), (C4), and (C5). Study abroad expenses are partially provided to successfully nominated students. Based on the Engineering Schools' funding policy for its international exchange program, financial support is provided for 1) Outbound students who will participate in research under the supervision of professors in the host university 2) Outbound students who will conduct research to broaden their own research field Students engaging in the following are NOT eligible to receive funding through this program. 1) Joint research between an overseas university and Tokyo Tech 2) Research related to students' thesis research or doctoral dissertation 3) Study abroad solely focusing on acquiring course credits
Call for Applications	Announcements will be made on the new launched Engineering Schools' website and also will be sent to each faculty who belongs to the Engineering Schools. Applications for (C1) will be processed only in January . Applications for (C5) will be processed as needed.
Eligibility	1) Students on leave of absence are NOT eligible. 2) Applicants planning to study in their home country are NOT eligible. 3) Consideration will be given to students who actively participate in international activities or classes held by the Engineering Schools or Tokyo Tech. Please mention this in the application form if you have such experiences. 4) Only students with a GPA of 2.3 (Maximum 3.0) or higher in the previous year are eligible to apply.
Language Proficiency Requirements	Applicants must satisfy the following English proficiency requirements: TOEFL iBT [®] score of 70 or higher and/or TOEIC score of 650 or higher. However, even if their score is below this level, students may apply for the program if they have special reasons (e.g., have proficiency in language used in the country where the host university is located, have good English conversation ability that is not reflected in the scores). In such cases, students must attach a statement (free format) explaining these skills to their application.
Screening Method	Face to face interview in English • An applicant will be interviewed by multiple faculty members for 10 minutes (The first 5 minutes is for self-introduction, motivation, and research plan presentation, the latter 5 minutes is for questions and answers) • An applicant is allowed to distribute A4-size handouts • An applicant is not allowed to read scripts or use a PC and/or projector Note: If the number of applicants is large, only those selected by the initial screening (examination of application documents) will be interviewed.
Financial Support for Outbound	• Round trip travel expense and/or scholarship is provided.

Students	<ul style="list-style-type: none"> • Application fees and expenses for visa acquisition are NOT provided. • In the case of Japanese government (MEXT) scholarship students, only the round trip travel expense (airfare) at cost is provided. Also please note that there might be a possibility for those who participate in this program to lose their eligibility to receive the MEXT scholarship not only during the stay abroad but also after coming back to Tokyo Tech. Please confirm the detailed and latest information about this with Student Support Division (gak.sei@jim.titech.ac.jp). • If other scholarships or financial support are provided to students by Tokyo Tech, the amount of the financial support under this program will be adjusted.
Important Points to Note	<ul style="list-style-type: none"> • Applicants must carefully determine their period of study abroad, taking into consideration the academic calendars of Tokyo Tech and the university in which they wish to enroll. The International Cooperation Office of the Engineering Schools will NOT coordinate schedules of students with classes or courses at Tokyo Tech. It is the applicant's responsibility to manage his/her own schedule. • Applicants for (C2) should note that some universities require applications to be completed approximately 3 months prior to enrollment.

◆ Grade Requirements

Students applying for categories (C1), (C2), (C3), and (C4) must state their GPA for the previous academic year in their application form. GPA must be calculated based on the calculation method below and applicants must have a GPA of 2.3 or higher.

How to calculate your Grade Point Average (GPA)

Grade Conversion Table						
	Grade					
Four-level grading scale (Type 1)	—	Excellent	Good	Fair	Fail	
Four-level grading scale (Type 2)	—	A	B	C	F	
Four-level grading scale (Type 3)	—	100–80	79–70	69–60	59 or lower	
Five-level grading scale (Type 4)	100–90	89–80	79–70	69–60	59 or lower	
Five-level grading scale (Type 5)	S	A	B	C	F	
Five-level grading scale (Type 6)	A	B	C	D	F	
Grade Evaluation Point (GEP)	3	3	2	1	0	

$$\frac{(\text{Number of Credit for GEP3} \times 3) + (\text{Number of Credit for GEP2} \times 2) + (\text{Number of Credit for GEP1} \times 1) + (\text{Number of Credit for GEP0} \times 0)}{\text{Total Number of Credits}}$$

First, refer to the above table to convert your grades to Grade Evaluation Points (GEP) and calculate the following.

- I The number of credits with a GEP of 3 multiplied by three
- II The number of credits with a GEP of 2 multiplied by two
- III The number of credits with a GEP of 1 multiplied by one
- IV The number of credits with a GEP of 0 multiplied by zero

To calculate your GPA, divide the sum of I, II, III, and IV by the number of total credits earned.

◆ Supplements

- The AOTULE and AOSU partner universities have their own requirements. See the links (C2-a: [AOTULE](#))(C2-b: [AOSU](#))
- Please read carefully our [FAQs](#) before contacting us.

* New requirements might be added. Please check out the latest information accordingly before you submit the applications. <http://www.eng3.e.titech.ac.jp>